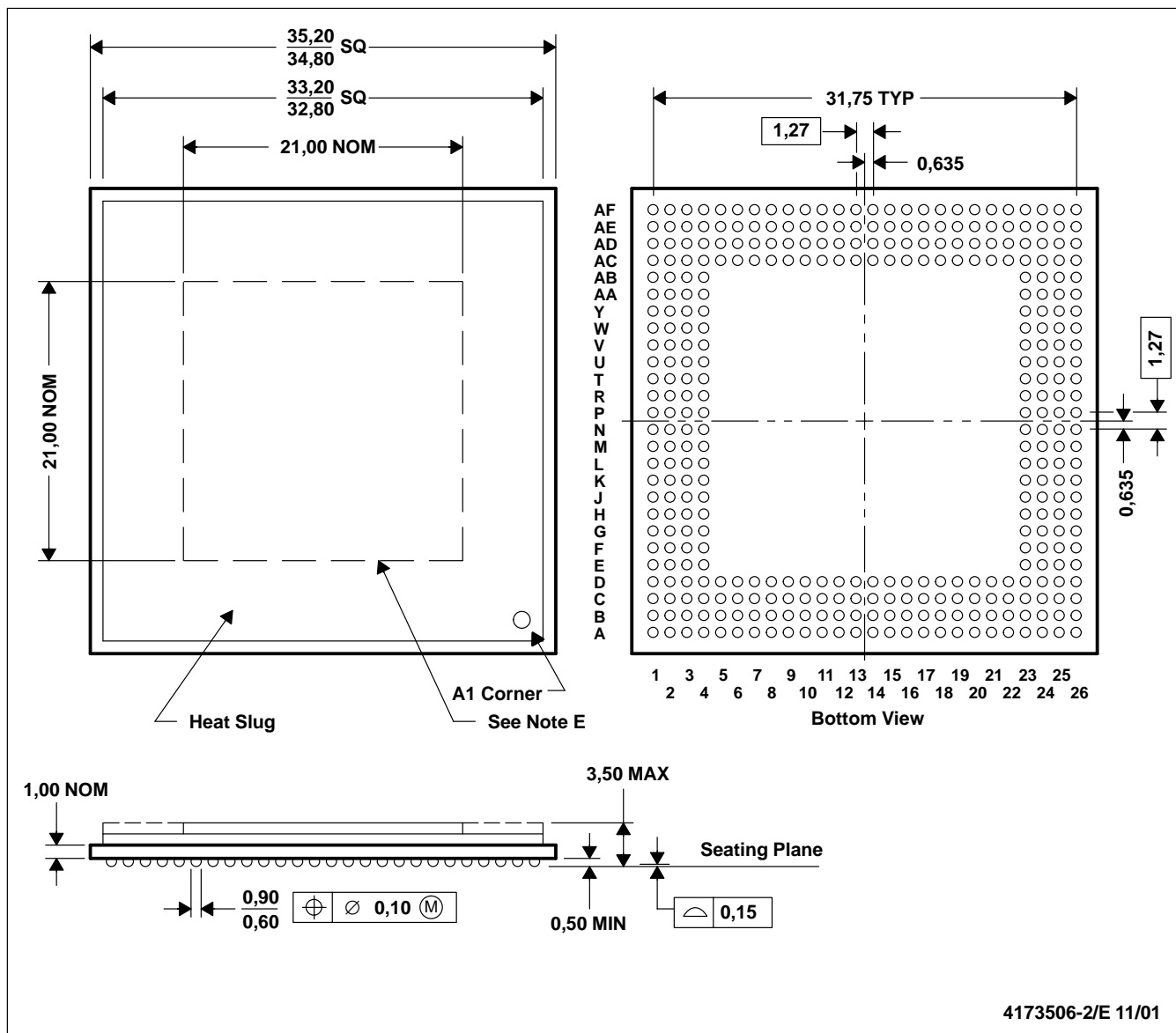


GJC (S-PBGA-N352)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced plastic package with heat slug (HSL).
 - D. Flip chip application only
 - E. Possible protrusion in this area, but within 3,50 max package height specification
 - F. Falls within JEDEC MO-151/BAR-2

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